

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

Claim 1 (Previously Presented): An implantable medical device comprising:

at least two interconnected modules, each of the modules comprising a respective one of at least two housings to house the respective modules; and

an overmold that at least partially encapsulates each of the housings and is at least partially flexible to allow relative motion between the modules, the overmold comprising a lead connection module configured to accept an external lead, wherein the external lead is separable from the lead connection module and wherein the lead connection module comprises a feed-through wire that electrically couples to the external lead.

Claim 2 (Original): The implantable medical device of claim 1, wherein at least one module comprises a control module containing electronic components.

Claim 3 (Previously Presented): The implantable medical device of claim 1, wherein the overmold comprises a first material and a second material, and the lead connection module is embedded within the first material.

Claim 4 (Original): The implantable medical device of claim 3, wherein the first material comprises a non-elastomeric material.

Claim 5 (Previously Presented): The implantable medical device of claim 1, wherein the feed-through wire electrically couples the external lead to an electronic component within the implantable medical device.

Claim 6 (Original): The implantable medical device of claim 1, wherein the lead connection module includes a mechanical lead securing mechanism.

Claim 7 (Original): The implantable medical device of claim 6, wherein the mechanical lead securing mechanism comprises a tool-less mechanical lead securing mechanism.

Claim 8 (Original): The implantable medical device of claim 1, wherein the implantable medical device has a maximum thickness of between approximately 4 millimeters and approximately 8 millimeters.

Claim 9 (Previously Presented): An overmold for a modular implantable medical device that includes a plurality of modules, each of the modules comprising a respective housing to house the respective module, the overmold comprising:

- a first material configured to hold at least part of the housing of one of the modules;
- a second material coupled to the first material, wherein at least one of the first or second materials is at least partially flexible to allow relative motion between the modules; and
- a lead connection module configured to accept an external lead, wherein the external lead is separable from the lead connection module, the lead connection module being embedded within the overmold, and wherein the lead connection module comprises a feed-through wire that electrically couples to the external lead.

Claim 10 (Original): The overmold of claim 9, wherein the first material comprises a non-elastomeric material.

Claim 11 (Canceled).

Claim 12 (Original): The overmold of claim 9, wherein the second material comprises silicone.

Claim 13 (Previously Presented): The overmold of claim 9, wherein the lead connection module is embedded within the first material.

Claim 14 (Original): The overmold of claim 9, wherein the lead connection module is configured to receive an iso-diametric external lead.

Claim 15 (Previously Presented): The implantable medical device of claim 1, wherein the housings are horizontally distributed at respective locations of the overmold, and separately encapsulated by the overmold.

Claims 16-18 (Canceled).

Claim 19 (Previously Presented): The implantable medical device of claim 2, wherein the housing of the control module is hermetic.

Claim 20 (Previously Presented): The overmold of claim 9, wherein at least one of the respective housings is hermetic.

Claim 21 (New): The implantable medical device of claim 1, wherein the overmold partially encapsulates each of the housings.